

# ACCESSORY EQUIPMENT

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High-quality accessory machines, a valuable addition to our dicing machine range, will facilitate dicing performance.



# ION WATER CLEANER

**NON-TOXIC GOOD FOR NATURE, GOOD FOR YOU**

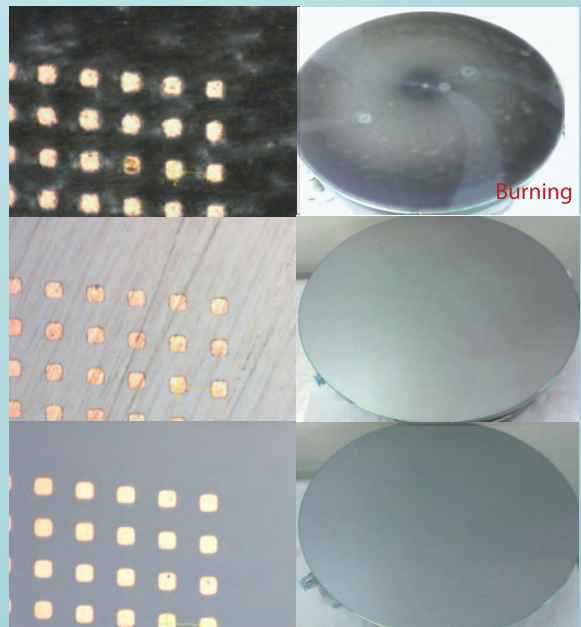
A brand-new ultrasonic cleaning machine with concern for the environment.  
No need of sewage treatment beacuse there is no use of acid-alkali liquid.  
Great effect on the treatment of heavy metal pollution (e.g. Cu+) to silicon work.

## MICROSCOPE VIEW

After Grinding + IWC Cleaning  
(W/O HPMJ) Resin #2000

After Grinding + IWC Cleaning  
(With HPMJ) Vitrified #8000

After CMP + IWC Cleaning



Cu Via Size : 5 $\mu$ m Pitch : 10 $\mu$ m



# NDS 412/408/406

## SPIN CLEANER

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### Cleaning Methods

Automatic with atomizing cleaning nozzle

### Stage type and size

Porous metal table

### Range of cleaning time

5 ~ 999 secs

### Applicable wafer size

12" / 8" / 6" / or under 6"

### PLC/Touch panel

PLC control system with touch panel

### Range of spinner revolution

400 r/min ~ 2800 r/ min

Different levels for speed adjustment

## SPECIFICATIONS

Items	Unit	NDS 412/408/406
Applicable Table		12 inch/8 inch/6 inch
Cleaning Methods		Atomizing cleaning nozzle
Revolution	rmp	400 ~ 2800
Centrifugal pressure	MPa	3.0 ~ 11.8
Power voltage		AC220V±10%
Power consumption	KW	Max 1.1
Compressed air pressure and deviation range	Mpa	0.5~0.7±0.01
Compressed air consumption	L/min	200
Nitrogen pressure and deviation range	MPa	0.2~0.4±0.01
Nitrogen consumption	L/min	100
Water pressure and deviation range	MPa	0.2 ~ 0.4±0.01
Water flow range	L/min	0.04 ~ 1.5
Exhaust duct capacity	m³/min	> 3
Dimensions	mm	450W × 950D × 1510H

\*Specifications are subject to change without notification.





# YM- Wafer Size S1-M

## WAFER POLISHING MACHINE

### High efficiency at low-cost

Advantages of using IWC (Liquid Water Content) inside the machine:

- increase cleaning capability
- lower DI water consumption
- save cost

### SPECIFICATIONS

Items	Wafer SPIN Cleaning Machine
Wafer size	3 / 4 / 6 / 8 / 12 inch
Chuck method	Pin Chuck Vacuum Chuck
Cleaning fluid	IWC (aqueous cleaner which does not contain a Surfactant) DIW
Washing method	A spot ultrasonic wave a PVA brush Vibrating body ultrasonic wave, etc.
Dryness revolution	~2,000rpm
Dry assistance	N2 blow Clean air blow
The cleaning room of processing area	Class 100
Washing time	2min~
Drying time	10sec~

\*Specifications are subject to change without notification.



# Suber

## ULTRASONIC CLEANING SYSTEM

### Ultimate perfect cleaning system

- Equipped with fluorinated detergent which can remove small particles
- Unique structure design which reduces detergent consumption
- Ultrasonic frequency: 40, 80, 120, 170KHz
- Single/ double/ triple/ quadruple frequency adjusting for different cleaning
- Vacuum ultrasonic power which provides better cleaning

# NDS 212/208

## WAFER MOUNT

- Suitable for 6", 8" and 12" wafer frames
- Compact desktop design
- Unsophisticated design, easy operation
- Reliable quality



### SPECIFICATIONS

Items	Unit	NDS 212	NDS 208
Workpiece Size		12 inch	8 inch
Rated voltage		AC 200V	
Frequency	Hz	50/60	
Power	W	≤700	
Air pressure	Mpa	0.5~0.7	
Machine weight	kg	60	
Machine dimensions	mm	1030x600x465	
Types of tape		Blue tape / White tape / UV tape	
Thickness of tape	mm	0.05~0.2	
Temperature of stage	℃	0~70	
Functions of tape mount		Manual	
Functions of tape cut		Rotation by manual	
Grounding resistance		below 4Ω	
*Specifications are subject to change without notification.			

Roller hardness can reach 30 degrees and bubble-free while tape mounting.

Wafer positioning accuracy : deviation with ±1mm .

Avoid damage to products by adjusting the height according to the thickness of products.

Equipped with tape retrieve system and suitable for double layer tape.

Range of heater : room temperature ~ 70 °C ,

Adjustable and accuracy in temperature control : ±2 °C

Avoid damage to wafer while mounting process by Teflon coating on the stage.

Stage can be designed to suit for different applications.

Throughput : more than 60 wafer/h.

ECD system is option.

# NDS 312/308

## CURING SYSTEM

- Applicable for 6", 8", 12" wafer frames
- Compact desktop design
- Uniform UV light
- Easy and safe to operate



### SPECIFICATIONS

Items	Unit	NDS 312/308
Rated Voltage	V	AC 220V
Electric Utility	Hz	50/60
Power	W	800
UV wavelength	nm	365
Dimension (LxDxH)	mm	700×660×380
Weight	kg	35
Applicable tape type		UV tape
Tape thickness	mm	0.15 ~ 0.17
Irradiation Function		Automatic
Grounding Resistance		below 4Ω

\*Specifications are subject to change without notification.

NDS Curing System, with LCD touch panel, can reduce the adhesive strength of all UV dicing tapes. Equipped with LED UV light rather than traditional mercury lamp, NDS curing system accommodates the benefits of longer life time, less heat, and lower power consumption.

The alarm buzzer is functioned if any problem occurs.